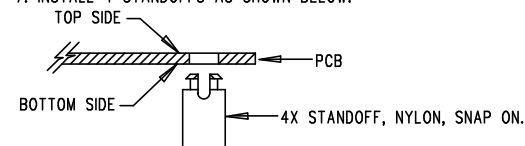


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PROTOTYPE	DB	08-11-20

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS

PCB DES.	LT	ANALOG DEVICES POWER BY LINEAR www.analog.com FOR ADI CUSTOMER USE ONLY		
APP ENG.	DB	TITLE: TOP ASSEMBLY DRAWING LOW IQ, DUAL, 100% DUTY CYCLE STEP-DOWN SUPPLY		
		SIZE	IC NO.	REV.
		N/A	LTC7805UFD DC3138A	1
SCALE = NONE		FILENAME: DC3138A-1.PCB		SHT 1 OF 2